

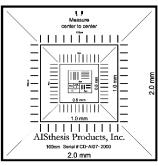
AISthesis Products

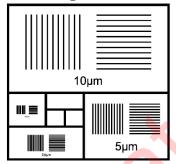
Advanced Imaging Products for Nanotechnology, Engineering and Life Sciences PO Box 1950, Clyde NC 28721





Wafer Level Certificate of Traceability for PelcotecTM Critical Dimension Magnification Standard





Product Number: Pelcotec™ 693-1 CDMS-XY-1T-ISO

Product Description: 2.5x2.5mm, Pelcotec™ 2mm-1μm

Critical Dimension Magnification Standard.

Wafer Serial Number: CD-AI07

As Received Condition: New

As Returned Condition: N/A

Date of Receipt: N/A

Customer name and contact information:



P.O. Box 492477

Redding, CA 96049-2477

Tel: 530.243.2200 www.tedpella.com

The accuracy of this product with Wafer Identifier CD-Al07 was determined using a Field Emission Scanning Electron Microscope (FE-SEM) by reference comparison to working standards traceable to the National Institute of Standards and Technology (NIST), using CP 01 FE-SEM Imaging of Critical Dimension Magnification Standards (CDMS) and CP 02 Certification of Critical Dimension Magnification Standards. Die were sampled according to method SOP 07 Sampling Die. The data applies only to the CDMS products identified in this report. All results are "as-is". Repair and/or adjustments are not possible.

Below are the ISO 17025:2017 Accredited Average 10 µm Pitch Measurements unique to Wafer Number CD-Al07 and traceable to NIST Certified Standard CD-PG01-0211.

X-Direction

Line	ISO 17025:2017 Accredited Average Pitch on Wafer	Position of Measurement
0-10 µm	10.011 µm	± 7.5 µm from center
10-20 μm	10.003 µm	± 7.5 µm from center
20-30 μm	10.012 μm	± 7.5 µm from center
30-40 μm	10.004 μm	± 7.5 µm from center
40-50 μm	10.011 μm	± 7.5 µm from center
50-60 µm	10.005 µm	± 7.5 µm from center

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60-70 µm	10.011 μm	± 7.5 µm from center
70-80 µm	10.006 μm	± 7.5 µm from center
80-90 µm	10.010 μm	± 7.5 µm from center
90-100 μm	10.005 μm	± 7.5 µm from center
Sum	<i>100.078</i> μm	
Average	10.0078 μm	
2-Sigma *	0.0094 µm	* Corrected for sample size

Y-Direction

Line	ISO 17025:2017 Accredited Average Pitch on Wafer	Position of Measurement	
0-10 µm	10.010 μm	± 7.5 µm from center	
10-20 µm	10.004 μm	± 7.5 µm from center	
20-30 μm	10.013 μm	± 7.5 µm from center	
30-40 μm	10.006 μm	± 7.5 µm from center	
40-50 μm	10.010 μm	± 7.5 µm from center	
50-60 μm	10.005 μm	± 7.5 µm from center	
60-70 μm	10.012 μm	± 7.5 µm from center	
70-80 µm	10.007 μm	± 7.5 µm from center	
80-90 µm	10.011 μm	± 7.5 µm from center	
90-100 μm	10.005 μm	± 7.5 µm from center	
Sum	<i>100.0</i> 83 μm		
Average	10.0083 µm		
2-Sigma *	0.0090 µm	* Corrected for sample size	using the appropriate Student t-factor.

using the appropriate Student t-factor.

Measurements are reported with an uncertainty $(k=2)^{**}$ of \pm 0.012 μ m. Statements of Conformity are not provided in this report. Review the results and verify that they meet the requirements for the intended use. Physical damage to or contamination of the CDMS occurring after calibration may invalidate the reported measurements. Use this product at 25°C \pm 5°C and at less than 80% RH.

Below are the Non-ISO 17025:2017 Accredited Average Pitch Measurements unique to Wafer Number CD-Al07 and traceable to NIST Certified Standard CD-PG01-0211.

X-Direction

Line	Number of Lines	Position of Measurement	Non-ISO 17025:2017 Accredited Measured Distance (first to last line)	Average Pitch of Wafer
2.0 mm	2	± 1.00mm from center	2.000 mm	2.000 mm
1.0 mm	2	± 0.5mm from center	1.000 mm	1.000 mm
0.5 mm	2	± 0.25mm from center	0.500 mm	0.500 mm
0.10 mm	2	± 0.125mm from center	1.001 mm	100.076 mm
5.0 µm	12	± 20 µm from center	55.019 μm	5.002 µm
2.0 µm	16	± 10 µm from center	30.039 μm	2.003 µm
1.0 µm	17	± 5 µm from center	16.021 μm	1.001 µm

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^{**} Reported uncertainties represent expanded uncertainties expressed at approximately the 95% confidence level using a coverage factor of k = 2. The reported expanded measurement uncertainty is stated as the standard measurement uncertainty multiplied by the coverage factor K such that the coverage probability corresponds to approximately 95%.

Y-Direction

Line	Number of Lines	Position of Measurement	Accredited Measured Distance	Average Pitch of Wafer
			(first to last line)	
2.0 mm	2	± 1.00mm from center	2.000 mm	2.000 mm
1.0 mm	2	± 0.5mm from center	1.000 mm	1.000 mm
0.5 mm	2	± 0.25mm from center	0.500 mm	0.500 mm
0.10 mm	2	± 0.125mm from center	1.001 mm	100.076 mm
5.0 µm	12	± 20 µm from center	55.019 μm	5.002 µm
2.0 µm	16	± 10 µm from center	30.039 μm	2.003 µm
1.0 µm	17	± 5 µm from center	16.021 μm	1.001 µm

The average pitch is derived from the stated length that was determined using measurements (taken center-to-center) over the stated number of lines (i.e., length divided by the number of lines minus one).

Date of Analysis: December 2nd, 2024

Equipment used:

Instrument	Model	Serial #	Resolution	Repeatability	Temperature	Humidity	Reference
FE-SEM	FEI Apreo2	9958357	0.9nm	0.030%	21.9 ± 0.1 °C	33.3 ± 0.8%	CD-PG01-0211

Location: AlSthesis Products, Inc., PO Box 1950, Clyde North Carolina 28721.

Notes:

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D.S. Finch	_	
Certified by	Signature	
H. Haehlen		<u>December 2nd, 2024</u>
Authorized by	Signature	Date report issued.

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End of report.